

PRODUCT NUMBER

10096501-T01-XXLF

INDICATES THE PRODUCT IS ROHS COMPATIBLE, SEE NOTE 6

NB OF POSITIONS PER ROW : 02 to 25.

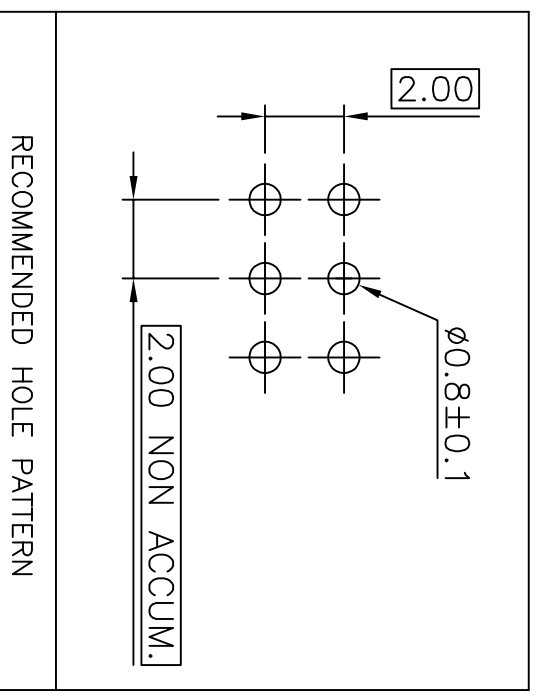
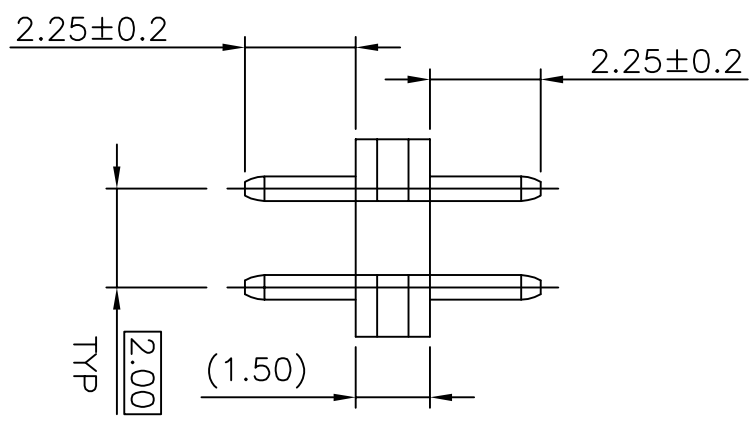
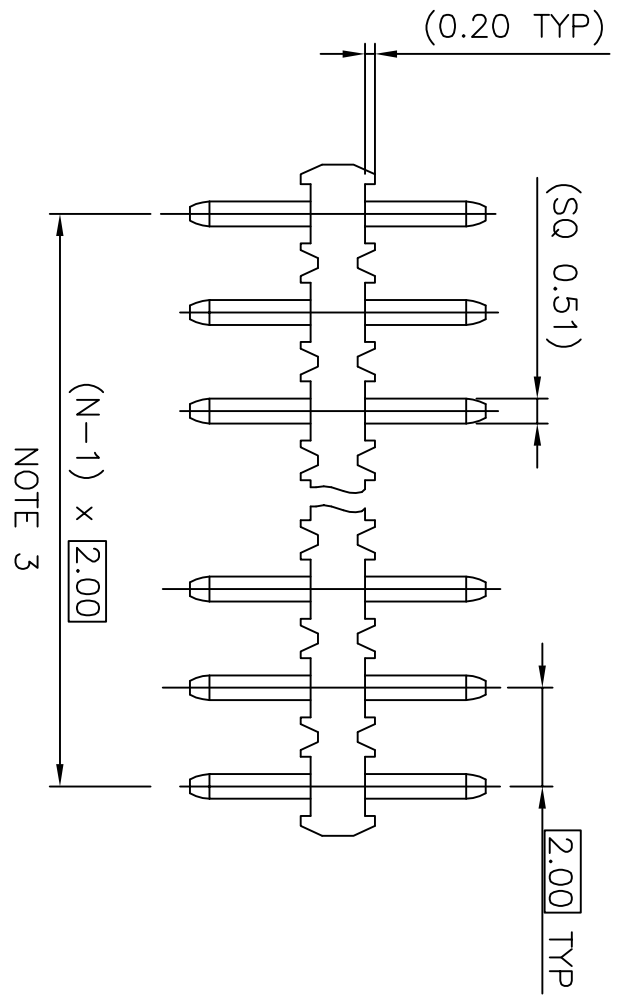
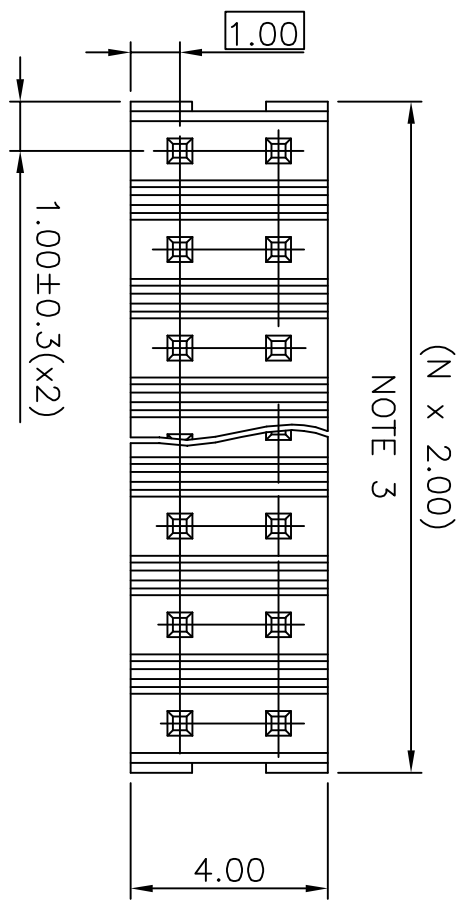
PLATING 2.0-6.0µm FULL MATTE TIN OVER 1.27µm NICKEL UNDERPLATING

NOTES:

1. MATERIAL HOUSING: HIGH TEMP. THERMOPLASTIC
UL 94V-0, COLOR BLACK
2. MATERIAL TERMINAL: COPPER ALLOY
3. TO DETERMINE DIMENSIONS:
N = NUMBER OF POSITIONS PER ROW
4. 7N MIN. PIN RETENTION IN EITHER DIRECTION.
5. PACKAGING: PLASTIC BOX
6. ROHS COMPATIBLE PRODUCT SPECIFICATIONS

- a - PLATING:
- "LF" MEANS THE PRODUCT IS LEAD-FREE, 2µm MINIMUM MATTE TIN OVER 1.27µm MINIMUM NICKEL UNDERPLATE.
- b - MANUFACTURING PROCESS COMPATIBILITY
- THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C ±5°C SOLDER BATH TEMPERATURE FOR 5 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.6mm MIN THICK CIRCUIT BOARD.
- COMPATIBLE TO REFLOW PROCESS 260°C MAX FOR 30 SECONDES
- c - LABELLING:
- MEETS PACKAGING SPECS AS PER GS-14-920
- d - LEGAL STATEMENT : SEE GS-47-0004

TOP VIEW



mat'l. code		surface		tolerance		projection		product family	
ISO 1302		ISO 406		ISO 101		mm		MINITEK	
A F09-0008 JCO		09.02.04		tolerances unless otherwise specified		101		title	
B B-19190 LMU		14.10.24		.X ±0.3		mm		UNSH HEADER	
				.XX ±0.13				2.00MM TMT FULL TIN	
				.XXX ±0.05				sheet 1 of 1	
				dr LMULIN				size	
				engr J.COMPAGNON				A3	
				chr				CUSTOMER Drawing	
				dppd JM.C					
				09.01.20					
sheet index		revision sheet							